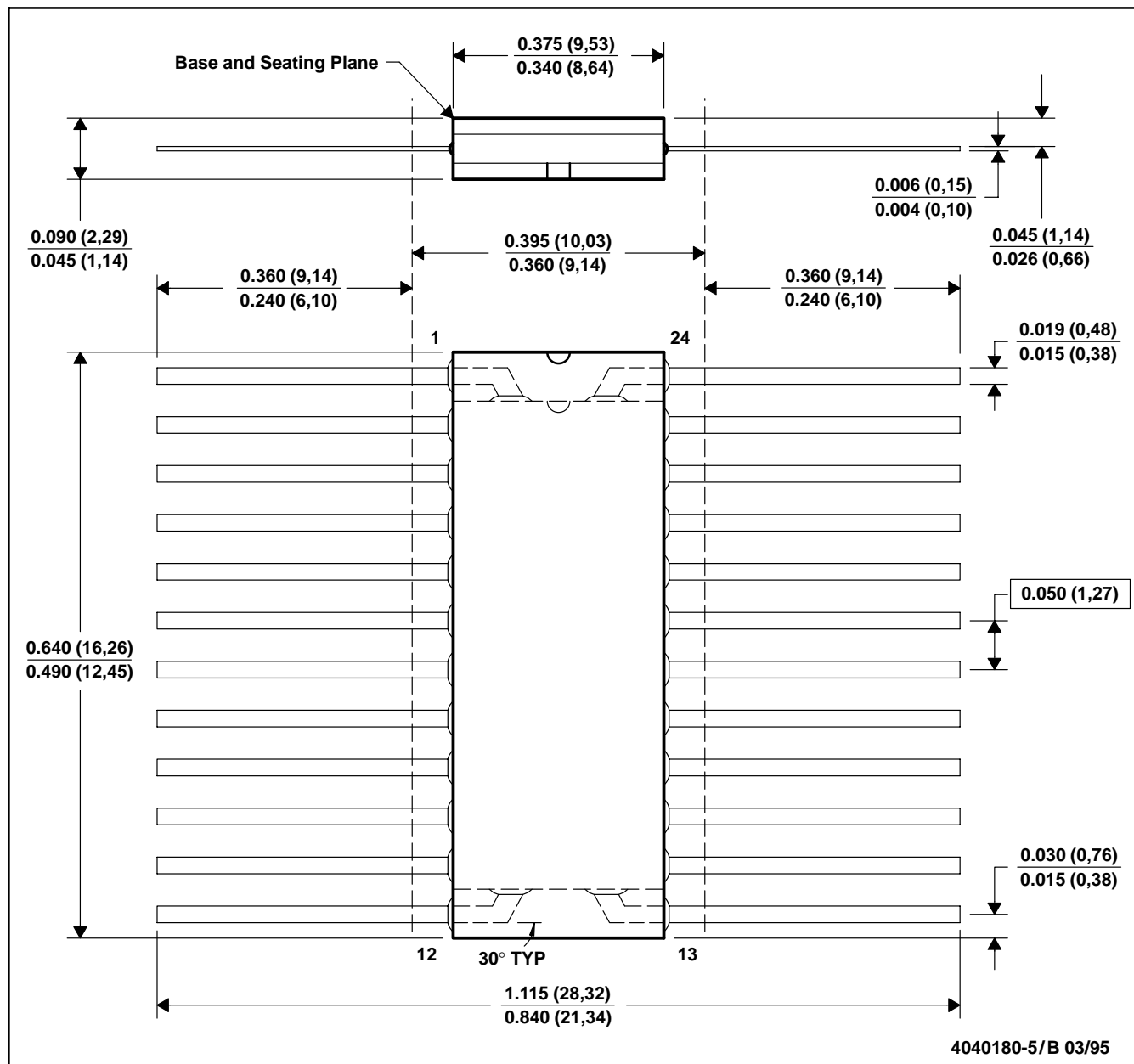


W (R-GDFP-F24)

CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Falls within MIL-STD-1835 GDFP2-F24 and JEDEC MO-070AD
 - Index point is provided on cap for terminal identification only.

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